A high-frequency level-up shifter based on 0.18µm vertical MOSFETs with more than 70% reduction of overshoot-voltage above VDD

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Abstract

A high frequency and high reliable level-up shifter is proposed. In the design, an initialize circuit, a voltage limiter and a dynamic biasing feed-back are added. In the simulation, our circuit based on 0.18 μ m vertical MOSFETs shows more than 70% reduction of the overshoot voltages above V_{DD} from the conventional. It achieves 164-MHz operation frequency with 2-pF loads at 1.8-V maximum voltage applied to the MOSFETS, which is larger than 1.6 times of the conventional frequency.

1. Introduction

Recently, many high-voltage tolerant level-up shifters using the thin-film MOSFETs for low V_{DD} have been developed for high frequency-switching in the power management systems[1]. Though the circuit is comparatively fast with high V_{DD} , the speed rapidly decreases as V_{DD} decreases. Thus, the further speed-advanced circuit has also reported[2]. In the circuit, however, the large overshoot voltages above V_{DD} are applied to the MOSFETs. To be overcome the problems, a new level-up shifter based on the vertical MOSFETs[3] with the dynamic biasing feed-backs is proposed. This paper describes our design and the excellent features.

2. Design for Overshoot Voltage reduction

Figure 1(a) and (b) show the conventional speed advanced level-up shifter[2] and our proposed one relatively. The input voltage swing between V_{DD} and 0V is converted to the swing between 2x V_{DD} and V_{DD} at Q, Qb. In our design, a voltage limiter VL(Fig. 1 (c)), a dynamic biasing feed-back BD(Fig. 1(d)), and N_{2l} , N_{2r} are added for the overshoot voltage reduction. INIT is initialize circuit. The overshoots arise at the output falling. Figure 2 shows the voltage waveforms in each circuit at the output falling. In the conventional, the level of Yb falls rapidly and Qb falls slow. Therefore, the large voltages(>>V_{DD}) are applied to the MOSFETs P_{21} , P_{11} at Qb falling. In our circuit(Fig. 2(b)), Vgs of P₂₁ is small enough, because of the voltage limiter. INIT, Pa5 and Na2 pre-charge to QG(QGb) at Q (Qb) rising. Thanks to the dynamic biasing feed-back, YGb becomes high-Z at Qb falling and the level drops momentary. Thus, Qb fall-time tf is reduced. Since Qb rapidly falls, the Vds overshoot of P_{11} is suppressed. Furthermore, N_{2l} , N_{2r} share the voltage drops.

3. Simulations

For the simulations, 0.18µm planar MOS parameters (typical) are used. The vertical MOSFET with the large Φ (around 0.18µm) can be approximated by the planar models without the back-bias effect[3]. Using the multi-pillar body-isolated vertical MOSFETs[3-4] shown in Fig. 3(a), the turn-on current I_b by the well-parasitic diode can be removed. Thus, JS of MOSFET models is set as zero(Fig. 3(b)). The gate width W₀ of a MOSFET pillar is set as 560nm (Φ =0.178µm) and number of pillar for each MOSFET is tuned for I_{ds} tuning as shown in Table. I.

The relations between the maximum voltages V_{gsmax}, V_{gdmax} , V_{dsmax} of the MOSFETs and number of pillar m_{p2} (for P_{2l} , P_{2r}) are shown in Fig. 4. The data with 3% or more overshoots are plotted. In the conventional, V_{gsmax}(or V_{gdmax}) overshoots above V_{DD} and V_{dsmax} one are larager than 0.62V, and 0.65V respectively. The overshoots of V_{gsmax}(or V_{gdmax}) and V_{dsmax} in our circuit are 0.08V(>87% reduction) and 0.16V(>75% reduction) respectively. The relations the maximum voltages to MOSFETs between and number of pillar m_{p1} (for P_{11} , P_{1r}) are shown in Fig. 5. The conventional V_{gsmax} (or V_{gdmax}) overshoots and V_{dsmax} one are larger than 0.63V, and 0.66V respectively. Those of V_{gsmax} (or V_{gdmax}) and V_{dsmax} in our circuit are 0.08V(>87%) reduction) and 0.19V(>71% reduction) respectively. Thus, the overshoot voltages of our circuit are reduced by 70% or more from the conventional.

Figure 6 shows the output rise time tr, the fall time tf and the power consumption P_{ower} in the conventional and the proposed. tr of the conventional is about same as that of the proposed. When m_{p2} increases, tf of the conventional decreases. tf of the proposed is about flat to m_{p2} . This reason is the main discharge-path difference; the paths of the conventional are P_{2l} , P_{2r} and those of the proposed are P_{1l} , P_{1r} . In the simulations, the speed optimized m_{p1} for the conventional and our proposed are 8 and 2 relatively.

The trade-off relations between the maximum voltage V_{MOSmax} applied to all MOSFETs voltages and the operation frequency f_{max} in the conventional and our circuit are shown in Fig. 7(a). The optimized m_{p1} for each circuit is used. f_{max} is calculated from tr and tf. Our circuit shows the highest frequency with the same V_{MOSmax} , and achieves 164MHz with 2-pF loads and 1.8-V V_{MOSmax} , which is larger than 1.6 times of the conventional[2]. The relations between the power consumption and f_{max} are shown in Fig. 7(b). The reverse current to V_{DD} is ignored. In P_{ower} - f_{max} trade-off, our circuit is very advantageous to the conventional for the conventional

tional[1] and is about same as the conventional[2].

4. Conclusions

The level-up shifters with applied voltage limiting is proposed. The circuit is designed using vertical MOSFET without the well-diode turn-on. In the simulations, the proposed circuit reduces the overshoot voltages above V_{DD} by 70% or more from the conventional, and achieves 164MHz at 1.8-V maximum voltages applied to MOSFETs, which is larger than 1.6 times of the conventional frequency.

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(a) Maximum Vgs, Vgd (b) Maximum Vds Fig. 5 Relations between m_{p1} and Maximum voltages to MOSFETs.



 $\begin{array}{c} (a)\ m_{p2}\ vs\ tr,\ tf \qquad (b)\ m_{p1}\ vs \\ Fig.\ 6\ Relations\ between\ m_{p2},\ m_{p1}\ and\ tr,\ tf. \end{array}$





Table. I Number of Pillars for each MOSFET's.

	Variables		Constants					
symbole in Fig. 1	P_{1l}, P_{1r}	P_{2l},P_{2r}	P_{0l},P_{0r}	N_{1l}, N_{1r}	N ₂₁ , N _{2r}	P _{aj}	N _{aj}	NMOS
						(j=1,2)	(j=1,2)	in INV
Number of Pillars	m _{p1}	m _{p2}	8	24	48	4	2	24
Range	8 to 32	48 to 72						